

CONTACT MANUFACTURER

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TECHNICAL DATA SHEET

PRODUCT:FO

SIZE:1500

FO IS A KIND OF GRINDING & LAPPING POWDER,A HIGH-PRECISION,ALUMINA-BASED ABRASIVE POWDER DESIGNED FOR FINE LAPPING AND SUREFACE FINISHING,ESPECIALLY FOR PRECISION LAPPING OF SEMICONDUCTOR DEVICE AND SILICON WAFERS.

AVERAGE CHEMICAL COMPOSITION(TYPICAL)

Size	S.G(g/cm3)	CHEMICAL COMPOSITION (%)				
		Al2O3	SiO2	Fe2O3	TiO2	ZrO2
#1500	≥3.90	≥40.5	≤20.0	≤0.7	≤2.0	≤33.0

PARTICLE SIZE DISTRIBUTION

Size	D0	D3	D50	D94
#1500	≤19.0	≤17.0	5.5±0.5	≥3.0

MAIN APPLICATIONS

--GRINDING AND POLISHING OF SEMICONDUCTOR WAFERS,SILICON WAFERS ETC
--SURFACE FINISHING OF VARIOUS OPTICAL GLASSES
--GRINDING AND POLISHING OF LENSES,PRISMS,MIRRORS,FILTERS,ETC
--SURFACE FINISHING OF PIEZOELECTRIC MATERIALS
--FIBER OPTIC FERRULES,LAPPING FILMS
--ALUMINA AND ALUMINUM NITRIDE SUBSTRATES;SEMICONDUCTORS CERAMIC COMPONENTS
--WAFER THINNING AND DOUBLE-SIDED GRINDING
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PACKAGING

10KGS PVC BAGS+ PALLET

The shown values are typical characteristics of the material and shall not be used to prepare specifications. They are submitted to tolerances of the production and meet the present standard of technique. We reserve our right for changes within the scope of technical progress or internal improvement..